

Vishay Siliconix

Dual N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)		
60	0.058 at V _{GS} = 10 V	5.3	13 nC		
	$0.072 \text{ at V}_{GS} = 4.5 \text{ V}$	4.7	13110		

FEATURES

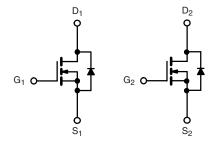
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET



ROHS COMPLIANT HALOGEN FREE

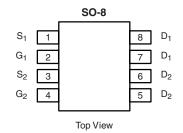
APPLICATIONS

- LCD TV CCFL Inverter
- Load Switch



N-Channel MOSFET

N-Channel MOSFET



Ordering Information: Si9945BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	60	.,		
Gate-Source Voltage	V_{GS}	± 20	V		
	T _C = 25 °C		5.3		
Continuous Dusin Comment (T., 150 °C)	T _C = 70 °C		4.3		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	4.3 ^{b, c}		
	T _A = 70 °C		3.4 ^{b, c}	_	
Pulsed Drain Current (10 μs Width)		I _{DM}	20	Α	
0 " 0 0 0 0	T _C = 25 °C	1	2.6		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S —	1.7 ^{b, c}		
Avalanche Current	L = 0 1 mH	I _{AS}	11		
Single-Pulse Avalanche Energy	L=UIIIII	E _{AS}	6.1	mJ	
	T _C = 25 °C		3.1		
Maximum Power Dissipation	T _C = 70 °C		2	10/	
	T _A = 25 °C	P _D	2 ^{b, c}	W	
	T _A = 70 °C		1.3 ^{b, c}		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, d}		R _{thJA}	55	62.5	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	33	40] O/VV	

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 110 $^{\circ}\text{C/W}.$

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SPECIFICATIONS T _J = 25 °C, unless otherwise noted								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static	1					ı		
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		55		mV/°C		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	_ ,		- 6				
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V		
	· GS(III)	$V_{DS} = V_{GS}$, $I_D = 5 \text{ mA}$		2.5		v		
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = 20 \text{ V}$			100	nA		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μА		
Zero date voltage Brain Garrent		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			10			
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 V$, $V_{GS} = 10 V$	20			Α		
Dunin Course On Chata Basistanas	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 4.3 \text{ A}$		0.046	0.058			
Drain-Source On-State Resistance ^a		$V_{GS} = 4.5 \text{ V}, I_D = 3.9 \text{ A}$		0.059	0.072	Ω		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 4.3 \text{ A}$		15		S		
Dynamic ^b								
Input Capacitance	C _{iss}			665				
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		75		pF		
Reverse Transfer Capacitance	C _{rss}			40				
Tatal Cata Chausa	Q_g Q_{gs} Q_{gd}	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4.3 \text{ A}$		13	20	nC		
Total Gate Charge				6	9			
Gate-Source Charge		$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 4.3 \text{ A}$		2.3				
Gate-Drain Charge				2.6				
Gate Resistance	R_g	f = 1 MHz		2		Ω		
Turn-On Delay Time	t _{d(on)}			15	25			
Rise Time	t _r	$V_{DD} = 30 \text{ V}, R_{L} = 8.8 \Omega$		65	100			
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 3.4 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		15	25			
Fall Time	t _f			10	15			
Turn-On Delay Time	t _{d(on)}	$t_{d(on)}$ t_r $V_{DD} = 30 \text{ V, R}_L = 8.8 \Omega$		10	15	ns		
Rise Time				15	25			
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 3.4 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		20	30			
Fall Time	t _f			10	15			
Drain-Source Body Diode Characterist	tics							
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			2.6			
Pulse Diode Forward Current	I _{SM}				20	A		
Body Diode Voltage	V_{SD}	I _S = 1.7 A, V _{GS} = 0 V		0.8	1.2	V		
Body Diode Reverse Recovery Time	dy Diode Reverse Recovery Time t _{rr}			30	60	ns		
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 1.7 A, dl/dt = 100 A/μs, T _J = 25 °C		32	50	nC		
Reverse Recovery Fall Time	ta			25		ns		
Reverse Recovery Rise Time	t _b			5				

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

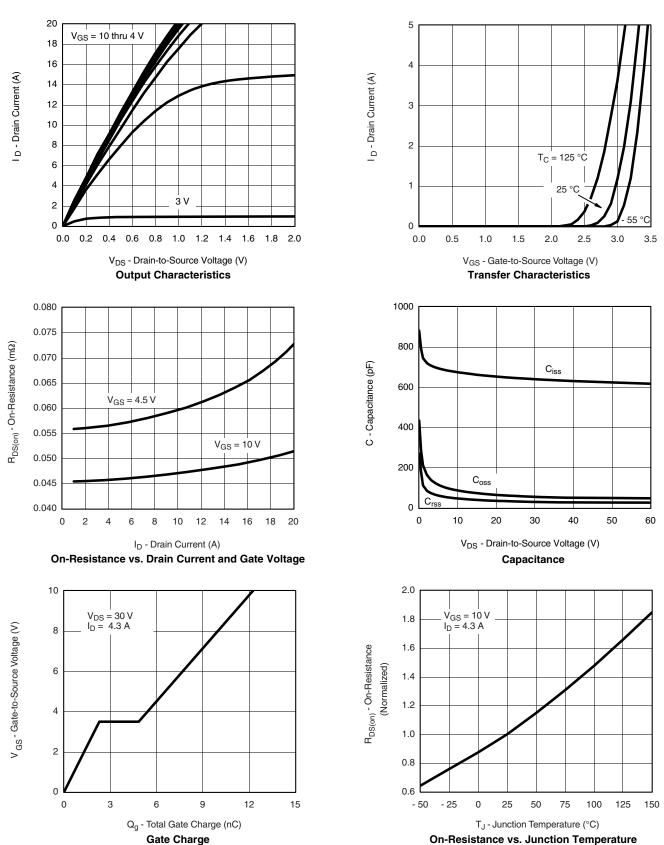
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

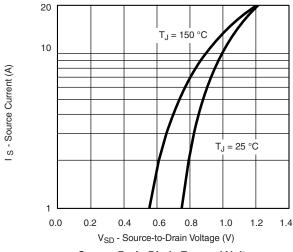


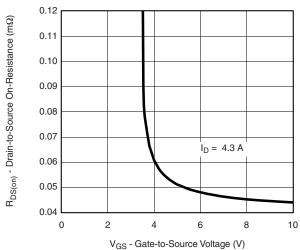
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Si9945BDY

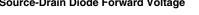
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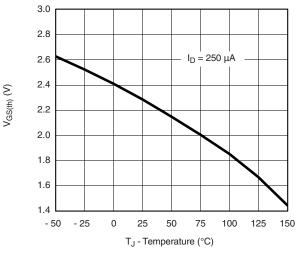
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



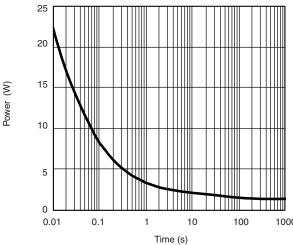


Source-Drain Diode Forward Voltage



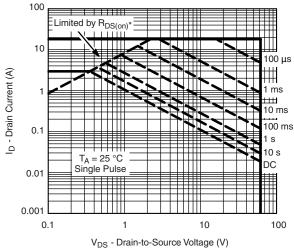


On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

Single Pulse Power, Junction-to-Ambient



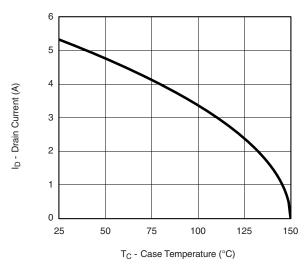
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

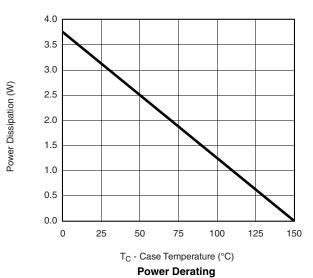
Safe Operating Area



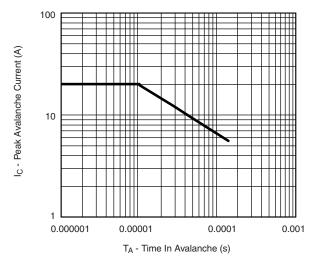
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted









Single Pulse Avalanche Capability

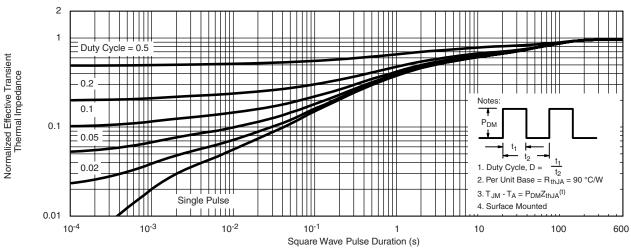
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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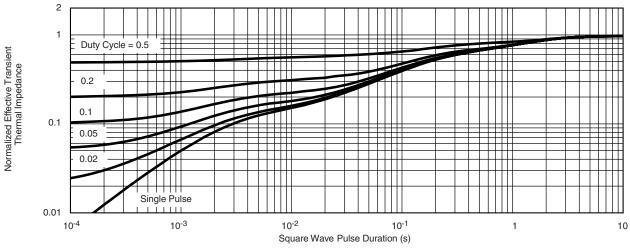
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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